Day 1 - Monday 20th April 2026

11:00	AngelTech Innovate Summit - Limited places! Requires separate registration: https://www.angeltech-innovate.net/register
18:00	Pre-conference Networking Drinks / Dinner Reception (available to those who have registered for 21st & 22nd April for AngelTech Conference)

Day 2 - Tuesday 21st April 2026

08:00	Registration and welcome refreshments
08:50	Housekeeping by Conference Chair
Heterogeneous Integration	
09:00	Silicon to Systems: How Advanced Packaging Is Redefining Performance Scaling *Presented by Diana Khlan - Chips Weekly*
09:20	Bridging the Gap: Collaborative Industry - Research Ecosystems in Advanced Packaging *Presented by Ulrike Ganesh - Fraunhofer IZM*
09:40	Sub-Micron Active Alignment: Enabling Advanced Packaging at the Nanometer Level *Presented by David Forer - Physik*
10:00	Heterogeneous Integration and Co-packaged Optics: Meeting AI Bandwidth Demand *Presented by Himani Suhag Kamineni - GlobalFoundries*
10:20	Advanced Photonic Assembly for Co-Packaged Optics *Presented by Bert Offrein - IBM*
10:40	Morning Break - Refreshments & Networking
11:10	Foundry 2.0: A New Foundation for Semiconductors and Innovation *Presented by Robert Patti - NHanced Semiconductors*
11:30	Localized Electrochemical Manufacturing (LEM): A Scalable High-Density Interconnect Platform for Next-Generation Heterogeneous Integration *Presented by Sebastiaan Muller - Syenta*
11:50	Thin Film Deposition Developments for Large Size Packages on Panel Scale *Presented by Andre Schenk - Evatec*
12:10	From Innovation to High-Volume Production: Scaling Heterogeneous Integration and Co-Packaged Optics *Presented by Anneirudh Sundararajan - PHIX Photonics Assembly*
12:30	Lunch Break, Networking & Posters
Manufacturing & Pilot Lines	
14:00	Supporting the European Advanced Packaging Ecosystem in HVM and Innovation *Presented by Eoin O'Toole - Amkor Technology*
14:20	Process Integration in Redistribution Layer Manufacturing *Presented by Bernhard Hammerl - Siconnex*
14:40	Assembly Design Kit Challenges and Opportunities *Presented by David Harame - AIM Photonics*
15:00	APECS Pilot Line: Shaping the Future of Heterogeneous Integration and Advanced Packaging *Presented by Johannes Rittner - FMD / APECS*
15:20	Advanced Photonics Packaging in the AI Era *Presented by Massimo Leo - Jabil*
15:40	Afternoon Break and Networking
Materials, Design and Reliability	
16:10	The European Chip Design Platform (EuroCDP): Enabling Access to Advanced Semiconductor Design in Europe *Presented by Helio Fernandez Tellez - imec*
16:30	From Miniaturization to System Integration: The Growing Role of Semiconductor Packaging *Presented by Dr. Pascal Oberndorff - NXP Semiconductors*
16:50	Next-Generation Silicon Photonics Platforms Enabled by Micro-Transfer Printing – The TRANSVERSE Pilot Line *Presented by Gunther Roelkens - Ghent University - imec*
17:10	Design Enablement of a Heterogeneously Integrated Electronic-Photonic System in a Package *Presented by Sylwester Latkowski - PITC*
17:30	Packaging Reliability for Space and High Reliability Environments *Presented by Finbarr Waldron - Tyndall National Institute*
17:50	Closing Remarks
18:00	Networking Drinks and Dinner Reception (concludes around 20:00)
18:30	AngelTech Rump Session - Bottlenecks & Battlegrounds: The Future of the AI Chip Ecosystem *Presented by David Cheskis - Square Zero Technologies, and Diana Khlan - Chips Weekly*

Day 3 - Wednesday 22nd April 2026

08:00	Registration and welcome refreshments
08:50	Housekeeping by Conference Chair

Advancing Thermal Management

09:00	Beating the Heat: Diamond as an Enabler for High-Performance Advanced Packages *Presented by Joana Mendes - Instituto de Telecomunicações*
09:20	Advanced Thermal Management in High-Power Electronics Packaging Using Metal-Diamond Composite Heat Spreaders *Presented by Zeina Abdallah - University of Bristol*
09:40	Direct Atomic Layer Processing (DALP®): Spatially Localized, Multi-Material Fabrication for Next-Generation Devices from Discovery to Manufacturing *Presented by Mira Baraket - ATLANT 3D*

Getting the Best Out of Incumbent Solutions

10:00	From Capability to Scale: Accelerating the Advanced Packaging Ecosystem *Presented by Dr Gladys Benghalia - National Advanced Semiconductor Packaging and Integration Centre (NASPIC)*
10:20	Beyond the Mask: Multibeam Laser Lithography for Cost-effective, Flexible, and High-Precision Advanced Packaging *Presented by Sander Schellingerhout - Raith*
10:40	Optimising Legacy Wet Strip for Advanced Packaging *Presented by Phillip Sundin - SHELLBACK Semiconductor Technology*
11:00	Morning Break and Networking
11:30	Beyond the Standard: Redefining Semiconductor Packaging as a Specialized OSAT *Presented by Daniel Lieske - AEMtec*
11:50	Medium Volume Production and Advanced Packaging in the UK *Presented by John Boston - Custom Interconnect*
12:10	Photonics Packaging Moving Toward Scalability for a Fast-growing Market *Presented by Eric Mounier - Yole Group*
12:30	Lunch Break, Networking & Posters

Optimising Packaging Architectures

13:40	Recent Developments in Advanced Heterogeneous 3D Integration at the Wafer Level *Presented by Jean-Charles Souriau - CEA Leti*
14:00	Photonic Wire Bonds and Facet-Attached Micro-Lenses: Enabling Scalable Integration of Lasers and PICs *Presented by Laura Horan - Vanguard Automation*
14:20	Advanced Metrology for the Challenges of Advanced Packaging *Presented by Simon Cannonier - cyberTECHNOLOGIES*
14:40	A Sustainable Dicing Innovation for Cutting-Edge Semiconductor Challenges *Presented by Christian Keil - Lidrotec GmbH*
15:00	Afternoon Coffee Break
15:30	Advanced Packaging Methods for Heterogeneous Integration *Presented by Travis Scott - Finetech GmbH*
15:50	Digital Coating: Scalable and Material Saving Material Deposition *Presented by David Volk - SUSS Micro Tec*
16:10	Accelerating the Future: Enabling the Next Era of Advanced Integration with Multibeam- High-Productivity E-Beam Lithography *Presented by Ken MacWilliams - Multibeam*
16:30	Eliminating Sub-Micron Alignment: Self-Aligned Cantilever Packaging for Scalable Silicon Photonics *Presented by Paul Marchal - Photon Bridge*
16:50	Closing Remarks

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